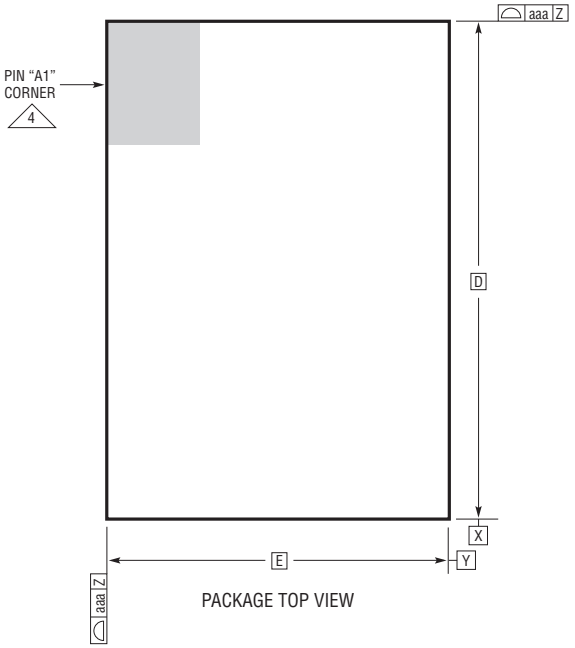
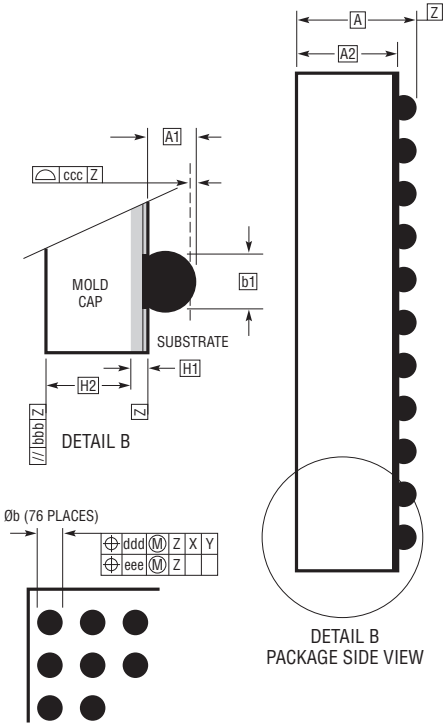
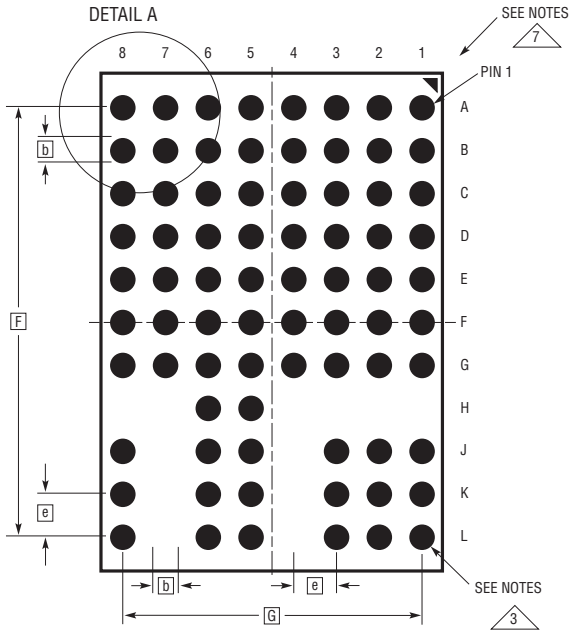
BGA Package
76-Lead (15mm × 11.25mm × 4.92mm)
(Reference LTC DWG # 05-08-1952 Rev Ø)

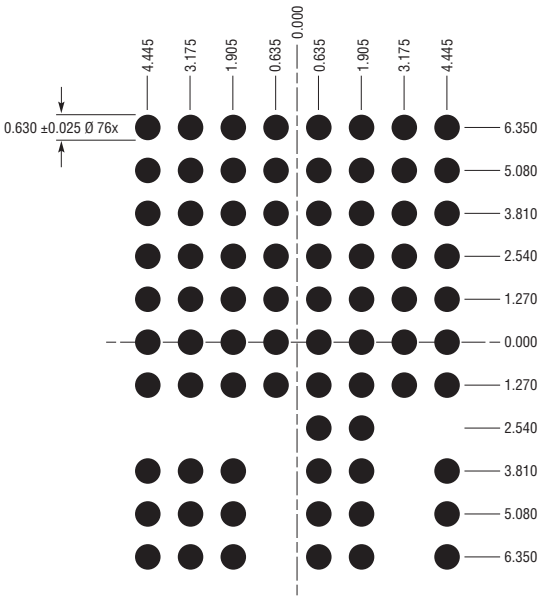


PACKAGE TOP VIEW





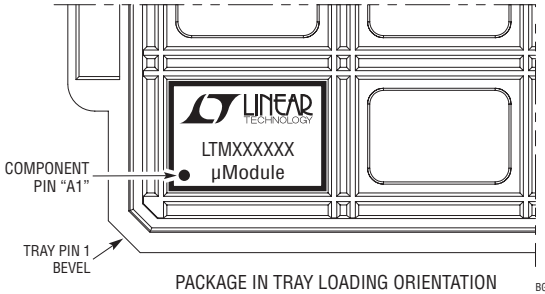
PACKAGE BOTTOM VIEW



SUGGESTED PCB LAYOUT
TOP VIEW

DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	4.72	4.92	5.12	
A1	0.50	0.60	0.70	
A2	4.22	4.32	4.42	
b	0.60	0.75	0.90	
b1	0.60	0.63	0.66	
D		15.00		
E		11.25		
e		1.27		
F		12.70		
G		8.89		
H1	0.27	0.32	0.37	
H2	3.95	4.00	4.05	
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.30	
eee			0.15	
TOTAL NUMBER OF BALLS: 76				

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS
3. BALL DESIGNATION PER JESD MS-028 AND JEP95
4. DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
6. SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu
7. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION

BGA 76 0513 REV Ø